



Dkt. 2271/71390

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of: Hitoshi ARITA and Akio KOJIMA

Serial No. : 10/701,061

Group Art Unit: 1725

Date Filed : November 4, 2003

Examiner: Jonathan J. Johnson

For: SOLDER ALLOY MATERIAL LAYER COMPOSITION, ELECTROCONDUCTIVE AND ADHESIVE COMPOSITION, FLUX MATERIAL LAYER COMPOSITION, SOLDER BALL TRANSFERRING SHEET, BUMP AND BUMP FORMING PROCESS, AND SEMICONDUCTOR DEVICE

Conf. No.: 5565

Class-Subclass: 228-254000

Issue Fee Due Date: September 19, 2005

Mail Stop Issue Fee

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

**APPLICANTS' COMMENTS ON
EXAMINER'S STATEMENT OF REASONS FOR ALLOWANCE**

Sir:

Applicant appreciates the Examiner's Statement of the Reasons for Allowance attached to the Notice of Allowability dated June 17, 2005 and submits that the allowed claims recite subject matter which further supports patentability for reasons in addition to those identified in the Reasons for Allowance.

Respectfully submitted,

PAUL TENG, Reg. No. 40,837
Attorney for Applicant
Cooper & Dunham LLP
1185 Avenue of the Americas
New York, N.Y. 10036
Tel.: (212) 278-0400

I hereby certify that this correspondence is being deposited this date with the U.S. Postal Service with sufficient postage as first class mail in an envelope addressed to: Mail Stop Issue Fee, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Paul Teng
Reg. No. 40,837

August 31, 2005
Date